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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ru-Gun Liu	05/22/2007
Chih-Ming Lai	05/22/2007
Wen-Chun Huang	05/24/2007
Boren Luo	05/28/2007
I-Chang Shin	05/24/2007
Yao-Ching Ku	05/18/2007
Cliff Hou	05/25/2007

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11748604

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 24061.802

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NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=assignment#page1.tif	
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PATENT REEL: 019616 FRAME: 0650 tulto 2007/05/10 \$8:38:35

Docket No.: 2006-0392 / 24061.802

Customer No.: 000042717

ASSIGNMENT

WHEREAS, We,

- (1) Ru-Gun Liu, of Hsinchu City, Taiwan, R.O.C.:
- (2) Chih-Ming Lai, of Hsinchu City, Taiwan, R.O.C.;
- (3) Wen-Chun Huang, of Xi-Gang Xiang, Tainan County, Taiwan, R.O.C.;
- (4) Boren Luo, of Hsinchu City, Taiwan, R.O.C.;
- (5) I-Chang Shin, of Hsinchu City, Taiwan, R.O.C.;
- (6) Yao-Ching Ku, Hsinchu City, Taiwan, R.O.C.; and
- (7) Cliff Hou, Taipei, Taiwan, R.O.C.

have invented certain improvements in

MODEL IMPORT FOR ELECTRONIC DESIGN AUTOMATION

for which we have executed and filed an application for Letters Patent of the United States of America,

on May 15, 2007, and which was assigned application serial number 11/748,604; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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[№]РАТЕМТ [№] РОВЕН: 019616 FRAME: 0651

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name:	Ru-Gun Liu	
Residence Address:	No. 9, Alley 19, Lane 452, Baoshan Rd. Hsinchu City 300 Taiwan, R.O.C.	
Dated: 5/11.	~~~ 7	Ry-Imn Liy
		Ru-Gun Liu (Inventor Signature)
Inventor Name:	Chih-Ming Lei	
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Dated: Chih Min	1 Lai 2007.05.22	Chih-Ming Lai Chih-Ming Lai (Inventor Signature)
		Cinii-wing Lai (inventor Signature)
Inventor Name:	Wen-Chun Huang	
Residence Address:	58, Zhong-Shan Rd., Xi-Gang Xi-Gang Xiang, Tainan County	Village y 723, Taiwan, R.O.C.
Dated: >7. 5.	مرد	Wen-Chun Iduang
		Wen-Chun Huang (Inventor Signature
Inventor Name:	Boren Luo	
Residence Address:	No. 8, Li-Hsin Rd. 6, Science Based Industrial Park Hsinchu, Taiwan 300-77, R.O.C	
Dated: 2007. 5	2.8	Boren Lun
		Boren Luo (Inventor Signature)

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Inventor Name:

I-Chang Shin

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Dated: 5/24 20°

I-Chang Shin (Inventor Signature)

Inventor Name:

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Dated: 5/18/2007

Yao Ching Ku (Inventor Signature)

Inventor Name:

Cliff Hou

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Dated: 5 /

Cliff Hou (Inventor Signature)

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